PCN Number:	20150306000**A**	**PCN Date:**	03/31/2015
Title:	Datasheet update for OPA192		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	06/31/2015		
Change Type:			

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

The product datasheet(s) is being updated as summarized below.

The following change history provides further details:

This information was previously communicated in 20150306000.

TEXAS INSTRUMENTS

OPA192, OPA2192, OPA4192

SBOS620B – DECEMBER 2013 – REVISED MARCH 2015 www.ti.com

Changes from Revision A (January 2014) to Revision B **Page**

- Added ESD Ratings and Recommended Operating Conditions tables, and *Parameter Measurement Information*, *Application and Implementation*, *Power-Supply Recommendations*, and *Device and Documentation Support* sections, and moved existing sections 1
- Changed all OPA192 and OPA2192 packages to production data 1
- Changed package names to latest standard; changed all MSOP to VSSOP, SO to SOIC, and SOT23 to SOT 1
- Deleted DCK package pin configuration 4
- Added thermal information for OPA192 DBV and DGK packages 6
- Added OPA2192 and OPA4192 Thermal Information tables 7
- Added rows with additional test conditions to input offset voltage parameter 7
- Changed Input offset voltage drift parameter 7
- Changed CMRR test conditions 8
- Added rows with additional test conditions to input offset voltage parameter 9
- Changed Input offset voltage drift parameter 9
- Changed PSSR parameter 9
- Changed CMRR test conditions 9
- Added *Output* section 10
- Added typical characteristic curves to Table 1 11
- Added T_A = 25°C to Typical Characteristics condition line 11
- Added nine new histogram plots from Figure 2 to Figure 10 12
- Changed Figure 11 to show more units 12
- Changed Figure 19 14
- Added text to *Application Information* section 30
- Changed text in *Layout Guidelines* section 34

This is updated information:

OPA192, OPA2192, OPA4192

SBOS620C – DECEMBER 2013 – REVISED MARCH 2015 www.ti.com

Changes from Revision B (March 2014) to Revision C	Page
• Added CDM row for OPA2192, OPA4192 in ESD Ratings table	6
• Changed input offset voltage values for $V_{CM} \geq (V+) - 1.5$ V test condition	7
• Changed Input offset voltage parameter typical specs for $V_{CM} = (V+) - 1.5$ V test conditions	7
• Changed test conditions for dV_{OS}/dT parameter	7
• Changed input offset voltage max values and test conditions for $V_{CM} = (V+) - 3$ V test condition	9
• Changed input offset voltage values and test conditions for $V_{CM} = (V+) - 1.5$ V test condition	9
• Changed Input offset voltage parameter typical specs for $V_{CM} = (V+) - 1.5$ V test conditions	9
• Changed test conditions for dV_{OS}/dT parameter	9
• Added text to last bullet of *Layout Guidelines* section	34

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPA192 OPA192	SBOS620A SBOS620B	**SBOS620B** **SBOS620C**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/opa192

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

To more accurately reflect device characteristics.

Changes to product identification resulting from this PCN:

None.

Product Affected:

OPA192ID	OPA192IDR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com